

FEATURES

- Dual-Role Port PD Compatible
- Attach/Detach Detection as Host, Device or DRP
- Current Capability Definition and Detection
- Cable Recognition
- Dead Battery Support
- VCONN Path Control
- Ultra-low Power Mode for Attach Detection
- Simple I²C Interface with Indication Pin
- Dual Slave Address for Dual Port Application
- BIST Mode Supported
- Programmable Default Settings
- 9-Ball WLCSP (WLCSP-9B) and 14-Lead QFN (QFN-14L) Packages

GENERAL DESCRIPTION

The **HUSB311** is a USB Type-C PD controller that complies with the latest USB Type-C and PD3.0 standards. It implements the USB Type-C port power control for VCONN, USB Type-C CC control and sensing and USB PD Message delivery. **HUSB311** has programmable R_p and R_d settings for each CC line. It does the USB type-C detection including attach and orientation. **HUSB311** integrates a complete BMC encoding including a receiver and transmitter. With this physical layer of the USB BMC power delivery protocol, **HUSB311** is able to handle the PD protocol and support any power up to 100W and perform role swap as needed. The BMC PD block enables full support for alternative interfaces of the Type-C specification.

HUSB311 uses I²C to communicate with the TCPM via employing an INT signal for requesting attention.

APPLICATIONS

- Smartphones
- Tablets
- Laptops
- Monitors

TYPICAL APPLICATION CIRCUIT

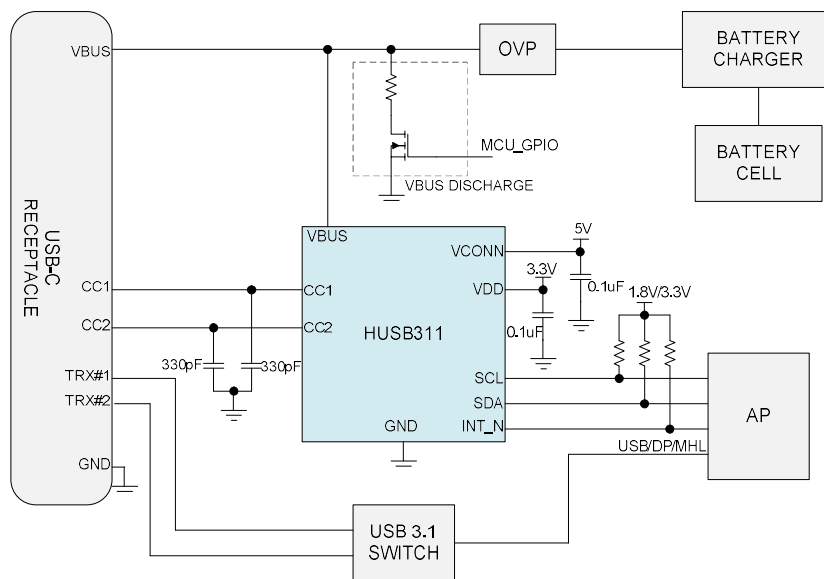


Figure 1. HUSB311 Typical Application Circuit

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REVISION HISTORY

Version	Date	Descriptions
Rev. 2.0	08/2021	Initial version
Rev. 2.1	12/2021	Update Package TOP Marking Add CDM ESD Rating Update Thermal Resistance
Rev. 2.2	01/2022	Update HUSB311_ALA to HUSB311_BLA
Rev. 2.3	03/2022	Update HUSB311_BLA Package Top Marking
Rev. 2.4	05/2022	Add Tape and Reel Information
Rev. 2.5	07/2022	ADD HUSB311_DCC& HUSB311_ELA Modify Tape and Reel Information
Rev. 2.6	03/2023	Modify the upper threshold of VCONN Present to 2.5V

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

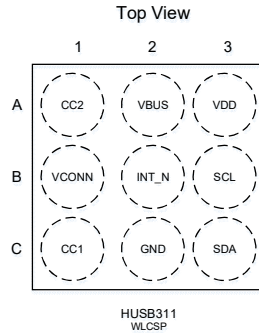


Figure 2. HUSB311_ACC& HUSB311_DCC Pin Assignment

Table 1. HUSB311_ACC& HUSB311_DCC Pin Function Descriptions

Pin No.	Pin Name	Type ¹	Description
A1	CC2	I/O	Type-C connector Configuration Channel (CC2) pins. Initially used to determine when a attach event has occurred and what the orientation detected.
A2	VBUS	A	VBUS input pin for attach and detach detection when operating as a Sink port (Device).
A3	VDD	P	Input supply voltage.
B1	VCONN	P	Regulated input pin connected to correct CC pin as VCONN to power Type-C full-featured cables and other accessories.
B2	INT_N	O	Active low and open drain type interrupt output used to prompt the processor to read the registers.
B3	SCL	I	I ² C serial clock signal connected to the I ² C master. The address is 0x4E or 0x3E.
C1	CC1	I/O	Type-C connector Configuration Channel (CC1) pins. Initially used to determine when a attach event has occurred and what the orientation detected.
C2	GND	A	Ground plane.
C3	SDA	I/O	I ² C serial data signal connected to the I ² C master.

¹ Legend:
A = Analog Pin
P = Power Pin
D = Digital Pin
I = Input Pin
O=Output Pin

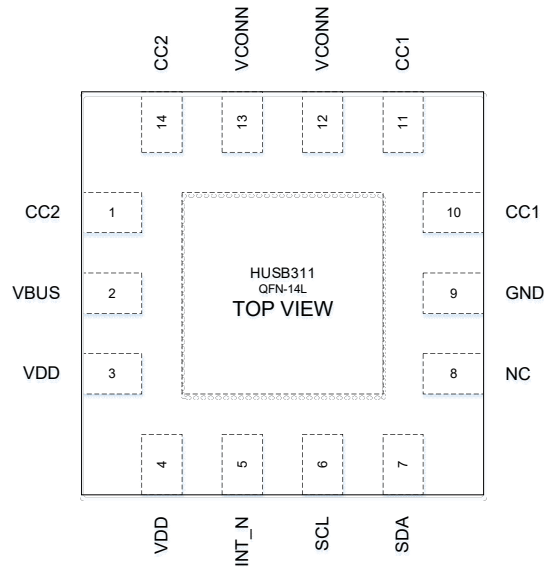


Figure 3. HUSB311_BLA& HUSB311_ELA Pin Assignment

Table 2. HUSB311_BLA& HUSB311_ELA Pin Function Descriptions

Pin No.	Pin Name	Type ¹	Description
1,14	CC2	I/O	Type-C connector Configuration Channel (CC2) pins. Initially used to determine when a attach event has occurred and what the orientation detected.
2	VBUS	A	VBUS input pin for attach and detach detection when operating as a Sink port (Device).
3,4	VDD	P	Input supply voltage.
12,13	VCONN	P	Regulated input pin connected to correct CC pin as VCONN to power Type-C full-featured cables and other accessories.
5	INT_N	O	Active low and open drain type interrupt output used to prompt the processor to read the registers.
6	SCL	I	I ² C serial clock signal connected to the I ² C master. The address is 0x4E or 0x3E.
10,11	CC1	I/O	Type-C connector Configuration Channel (CC1) pins. Initially used to determine when a attach event has occurred and what the orientation detected.
8	NC	A	Not connected pin. This pin can be floating or connected to GND directly.
9	GND	A	Ground plane.
7	SDA	I/O	I ² C serial data signal connected to the I ² C master.

¹ Legend:

A = Analog Pin

P = Power Pin

D = Digital Pin

I = Input Pin

O = Output Pin

RECOMMENDED OPERATING CONDITIONS**Table 3.**

Parameter	Rating
Supply Input Voltage	3.0 V to 5.5 V
VCONN Input Voltage	3.3 V to 5.5 V
VCONN Supply Current	0 to 600 mA
VCONN Supply Voltage	3 V to 5.5 V
Operating Temperature Range (Junction)	-40 °C to 125 °C
Ambient Temperature Range	-40 °C to 85 °C

SPECIFICATIONS

V_{DD} = 3.3 V and T_A = 25 °C for typical specifications, unless otherwise noted.

Table 4.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
GENERAL PARAMETERS						
Supply Voltage	V _{DD}		3		5.5	V
Supply UVLO Voltage	V _{UVLO_R}	Rising edge		2.7		V
	V _{UVLO_F}	Falling edge		2.64		V
DRP Toggle Current consumption	I _{Q_DRP}	CC1/2 are toggling and not attached. VCONN=5V, VDD current		33		μA
	I _{VCN5V_DRP}	CC1/2 are toggling and not attached. VCONN=5V, VCONN current		20		μA
	I _{Q_DRP1}	CC1/2 are toggling and not attached. VCONN=0V		33		μA
Operation Current	I _{CC_OPR}	CC is attached with R _p and in Bus Idle status		2		mA
Type C CC Logic						
Pull-down Voltage in Dead Battery Mode with Source Default R _p	V _{RDB_DEF}	Source Default R _p is 80μA±20%	0.25		1.5	V
Pull-down Voltage in Dead Battery Mode with Source 1.5A R _p	V _{RDB_1.5A}	Source Default R _p is 180μA±8%	0.45		1.5	V
Pull-down Voltage in Dead Battery Mode with Source 3A R _p	V _{RDB_3A}	Source Default R _p is 330μA±8%	0.85		2.5	V
R _d in Active Mode	R _d	V _{DD} >V _{UVLO} , CC is configured as R _d	4.6	5.1	5.6	kΩ
Attach Detection Threshold in Sink Mode	vR _{d_Snk}	With R _p is connected externally, CC is configured as R _d	0.25		2.04	V
Default Pull up current source in Source Mode	I _{RP_DEF}	CC is configured as Default R _p	64	80	96	μA
1.5A Pull up current source in Source Mode	I _{RP_1P5}	CC is configured as 1.5A R _p	166	180	194	μA
3A Pull up current source in Source Mode	I _{RP_3P0}	CC is configured as 3A R _p	304	330	356	μA
Attach Detection Threshold in Source Mode	vR _{d_Src}	With R _d is connected externally, CC is configured as Default R _p	0.25		1.5	V
		With R _d is connected externally, CC is configured as 1.5A R _p	0.45		1.5	V
		With R _d is connected externally, CC is configured as 3A R _p	0.85		2.45	V
PD BMC						
Bit Rate	f _{BitRate}		270	300	330	kbps
Maximum difference between the bit-rate during the part of the packet following the Preamble and the reference bit-rate	ρ _{BitRate}				0.25	%
Time from the end of last bit of a Frame until the start of the first bit of the next Preamble	t _{InterFrameGap}		25			μs
Time before the start of the first bit of the Preamble when the transmitter shall start driving the line	t _{StartDrive}		-1		1	μs
Time to cease driving the line after the end of the last bit of the Frame	t _{EndDriveBMC}				23	μs

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
Fall Time	t_{Fall}	10 % and 90 % amplitude points, with CC pin load of 200pF and 5.1K Ω in parallel	300			ns
Time to cease driving the line after the final high-to-low transition	$t_{HoldLowBMC}$		1			μ s
Rise Time	t_{Rise}	10 % and 90 % amplitude points, with CC pin load of 200pF and 5.1K Ω in parallel	300			ns
Voltage Swing	vSwing	With CC pin load of 1.2nF and 5.1K Ω in parallel	1.05	1.125	1.2	V
TX Output Impedance	ZDriver	BMC Tx output impedance while HUSB311 is driving the CC line	33	50	75	Ω
Time window for detecting non-idle	$t_{TransitionWindow}$		12		20	μ s
Receiver Input Impedance	ZBMCRx		1			M Ω
VCONN Source Control						
VCONN FET Conduction Resistance	RVCN				1	Ω
VCONN OC Threshold	I _{VCN_OC}			650		mA
VCONN Present Threshold	V _{VCN_PRS}		2		2.5	V
Time for VCONN to turn on	t_{VCN_ON}	VCONN=5V and EN_VCONN=1b		300		μ s
VBUS Detection						
VBUS Present Threshold	V _{VBUS_PRS_F} V _{VBUS_PRS_R}	Assert VBUS_PRESENT bit Set VBUS_PRESENT bit		3.8 4		V V
VBUS vSave0V	vSafe0V	To trigger VBUS_80 interruption		0.8		V
VBUS Measure Range	V _{VBUS_M_RG}		4		22	V
VBUS Measure Step	LSB _{VBUS_M1}} LSB _{VBUS_M2}}	VBUS=4-10V VBUS=10-20V		0.5 1		V V
I ² C Electrical Characteristics						
SCL Clock Frequency	f _{SCL}		50		1000	kHz
I ² C Bus Supply Range	V _{DD_I2C}		1.5		3.6	V
Low Level Input Voltage	V _{IL}				0.4	V
High Level Input Voltage	V _{IH}		1.2			V
Low Level Output Voltage	V _{OL}	Open Drain Output, Sink Current=2mA			0.4	V
Input Current Each IO Pin	I _I	With 0.9V _{DD} applied	-10		10	μ A
Pulse width of spikes that must be suppressed by the input filter	t_{sp}				50	ns
Data Hold Time	$t_{HD:DAT}$		0			μ s
Data Set-Up Time	$t_{SU:DAT}$		50			ns
Leakage Current Each IO Pin	I _{LKG}	With VDD_I ² C on each pin, VDD=5V	-1		1	μ A
INT_N PIN						
Leakage Current	I _{LKG}		-1		1	μ A
Low Level Output Voltage	V _{OL}	Sink Current=2mA			0.4	V

ABSOLUTE MAXIMUM RATINGS

Table 5.

Parameter	Rating
VBUS	-0.3 V to 30 V
CC1,CC2	-0.3 V to 24 V
VDD, VCONN, INT_N, SCL, SDA	-0.3 V to 6 V
Junction Temperature	150 °C
Storage Temperature Range	-65 °C to 150 °C
Soldering Conditions	JEDEC J-STD-020
Electrostatic Discharge (ESD)	
Human Body Model	±2000 V
Charged Device Model	±500 V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Close attention to PCB thermal design is required.

θ_{JA} is the natural convection junction to ambient thermal resistance measured in a one cubic foot sealed enclosure.

θ_{JC} is the junction to case thermal resistance.

Table 6. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
QFN-14L	106	10.8	°C/W
WLCSP-9B	118.3	68.9	°C/W

ESD CAUTION



Electrostatic Discharge Sensitive Device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

FUNCTIONAL BLOCK DIAGRAM

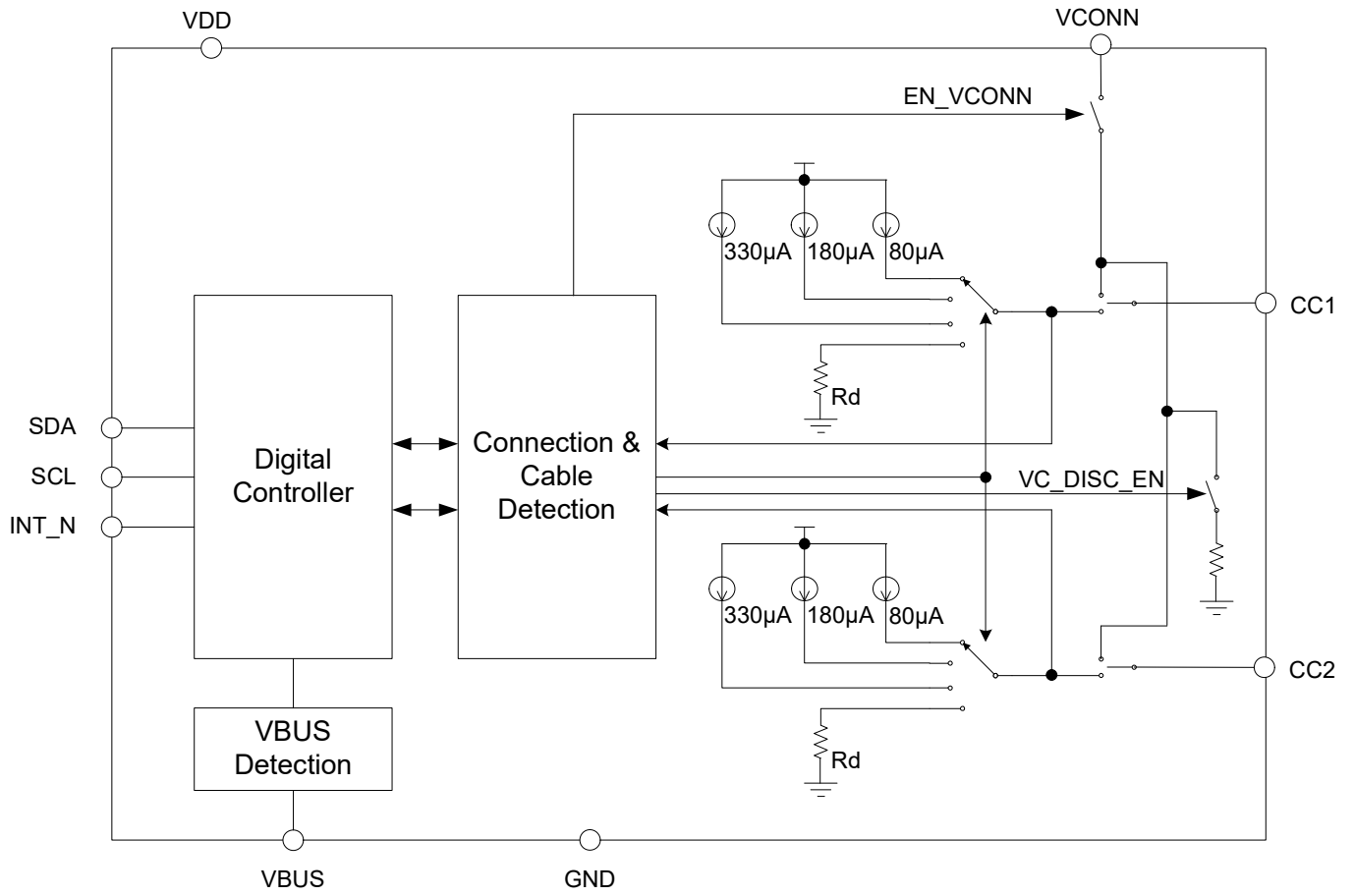


Figure 4. HUSB311 Functional Block Diagram

THEORY OF OPERATION

HUSB311 is a USB type C Port Controller (TCPC). It is a PD PHY level controller which handles VBUS and VCONN power connections, CC logic and USB PD message delivery through a simple register interface. **HUSB311** implements the portion of protocol layer in the USB PD specification. It sends and receives messages constructed in the TCCP and places them on the CC connections. **HUSB311** implements the following portions of the USB PD protocol layer:

- CRCReceiverTimer(PRL_Tx_wait_for_Phy_Response_state)
- RetryCounter(PRL_Tx_Check_RetryCounter State)
- Message ID is not checked in **HUSB311** when a non-GoodCRC message is received. Retried messages that are received are passed to the TCCP via I²C
- A message transmission is considered successful after receiving a GoodCRC response with the matching MessageID and SOP type

Two ways allow for asynchronous messages are received (see 0x50 definition).

Two way to handle BIST mode (see 0x19 definition).

COMMUNICATION BUS

HUSB311 communicates with TCCP via I²C bus. Two slave addresses are supported for **HUSB311**, 0x4E and 0x3E. It incorporates the I²C spec combined portion of SMBUS. There is an open drain active low output pin INT to indicate a change of state.

Some register of **HUSB311** is 16-bit. It is important to access this register by writing or reading at the first address. See more details in the Register Map.

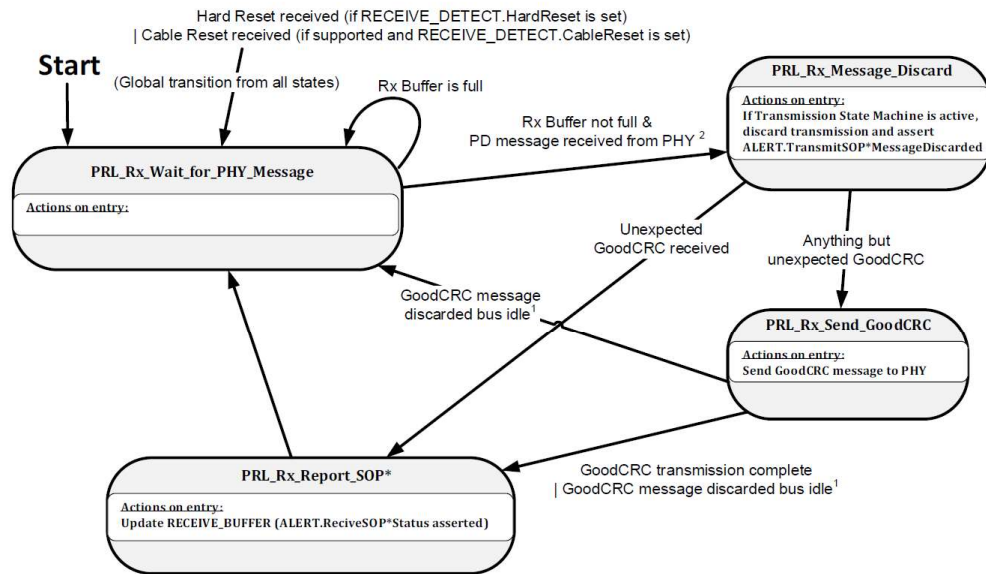
Once TCCP writes to a register or a bit that is reserved, **HUSB311** ignores and does nothing.

RX BUFFER

HUSB311 implements an Rx buffer for PD message reception. The main purpose of Rx buffer is:

1. Rx buffer is able to handle two set of 32 bytes data (1 byte Count number + 1 byte Frame type + 2 bytes Message Header+ 28 bytes data)
2. When there are already two sets of data stored in Rx buffer and the rest set of registers is 0, **HUSB311** is not able to respond any following PD message (NOT include the CableReset, HardReset) unless TCCP reads Rx buffer and clear the RX_BUF by set Alert.RX_SOP_MSG_STATUS and Alert.RXBUF_OVERFLOW

HUSB311 performs RX_BUFF as following state diagram. To start this state diagram, it depends on the RECEIVE_DETECT register settings (0x2F). If a not enabled type of message is received, the state will not change anything. Please note that if an unexpected GoodCRC is received during the transition, this unexpected GoodCRC should be treated as a command PD message.



¹ This transition is taken by the TCPC when the GoodCRC message has been discarded due to CC being busy, and after CC becomes idle again (see USB PD specification). Two alternate allowable transitions are shown.
² Messages do not include Hard Reset or Cable Reset signals, or expected GoodCRC messages (GoodCRC message is only expected after the TCPC has sent a PD message, and the TCPC Protocol Layer State Machine is in *PRL_Tx_Wait_for_PHY_Response*).

Figure 5. Rx_BUFFER State Machine Diagram

After the GoodCRC according to the received PD message is sent in PRL_Rx_Send_GoodCRC, HUSB311 is going to PRL_Rx_Report_SOP* state and assert INT_N pin for attention.

TCPM handles the Alert interruption after INT_N is asserted. The Rx Buff is accessed by TCPM to transmit the data. TCPM should clean the RX_BUFFER by writing Alert[2]=1. Once HUSB311 receives the write command to set Alert[2]=1.

DEAD BATTERY MODE

Low battery power could cause conditions in which communication over USB Type-C can no longer be maintained. When this situation occurs, it is critical to transition to attached.SNK state so that power from VBUS can be used to charge the battery back to an operational level. This condition is known as Dead Battery Mode.

The HUSB311 supports dead-battery mode by presenting Rd to both CC pins when VDD is no longer active.

In the dead-battery mode access to HUSB311 registers is not available. Upon exiting dead-battery mode, the HUSB311 enters mode dictated by the value of ROLE_CONTROL register (Register 0x1A).

REGISTERS

HUSB311 has several registers to configure the functions. The registers are accessed by the I²C address of 0x4E or 0x3E. The detailed function is defined as below:

Table 7. Register Map

Add	Register Name	Bit	Filed	Default	Type	Description
0x00	VENDOR_ID	7:0	VID[7:0]	0x99	R	A unique 16-bit unsigned integer Assigned by the USB-IF to the Vendor
0x01		7:0	VID[15:8]	0x2E	R	
0x02	PRODUCT_ID	7:0	PID[7:0]	0x11	R	A unique 16-bit unsigned integer. Assigned uniquely by the Vendor to identify the HUSB311
0x03		7:0	PID[15:8]	0x03	R	
0x04	DEVICE_ID	7:0	DID[7:0]	0x00	R	A unique 16-bit unsigned integer. Assigned by the Vendor to identify the version of the HUSB311
0x05		7:0	DID[15:8]	0x00	R	
0x06	USBTYPEC_REV	7:0	USBTYPEC_RE V	0x11	R	Version number assigned by USB-IF (Currently at Revision 1.1 – 0001 0001)
0x07		7:0	Reserved	0	R	
0x08	USBPD_REV_VER	7:0	USBPD_VER	0x11	R	0001 0000 – Version 1.0 0001 0001 – Version 1.1 Etc
0x09		7:0	USBPD_REV	0x20	R	0010 0000 – Revision 2.0
0x0A	PD_INTERFACE_R EV	7:0	PDIF_VER	0x10	R	0001 0000 – Version 1.0 0001 0001 – Version 1.1 etc.
0x0B		7:0	PDIF_REV	0x10	R	0010 0000 – Revision 1.0
0x10	ALERTL	7	ALARM_VBUS_ VOLTAGE_H	0	R	Not support
		6	TX_SUCCESS	0	RW	0b: Cleared 1b: Reset or SOP* message transmission successful
		5	TX_DISCARD	0	RW	0b: Cleared 1b: Reset or SOP* message transmission not sent due to incoming receive message
		4	TX_FAIL	0	RW	0b: Cleared 1b: SOP* message transmission not successful, no GoodCRC response received on SOP* message transmission
		3	RX_HARD_RES ET	0	RW	0b: Cleared 1b: Received Hard Reset message
		2	RX_SOP_MSG_ STATUS	0	RW	0b: Cleared 1b: RECEIVE_BUFFER register changed
		1	POWER_STATU S	0	RW	0b: Cleared 1b: Port status changed
		0	CC_STATUS	0	RW	0b : Cleared 1b : CC_STATUS is changed
0x11	ALERTH	7	Reserved	0	R	Not support
		6	Reserved	0	R	Not support
		5	Reserved	0	R	Not support
		4	Reserved	0	R	Not support
		3	Reserved	0	R	Not support
		2	RXBUF_OVFLO W	0	RW	0b: HUSB311 Rx buffer is functioning properly 1b: HUSB311 Rx buffer has overflowed

Add	Register Name	Bit	Filed	Default	Type	Description
0x12	ALERT_MASKL	1	FAULT	0	RW	0b: No Fault 1b: A Fault has occurred
		0	Reserved	0	R	Not support
		7	M_ALARM_VBUS_VOLTAGE_H	1	R	Not support
		6	M_TX_SUCCESSES	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		5	M_TX_DISCARD	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		4	M_TX_FAIL	1	RW	0b: Interrupt masked 1b : Interrupt unmasked
		3	M_RX_HARD_RESET	1	RW	0b : Interrupt masked 1b : Interrupt unmasked
		2	M_RX_SOPMSG_STATUS	1	RW	0b : Interrupt masked 1b : Interrupt unmasked
		1	M_POWER_STATUS	1	RW	0b : Interrupt masked 1b : Interrupt unmasked
0x13	ALERT_MASKH	0	M_CC_STATUS	1	RW	0b : Interrupt masked 1b : Interrupt unmasked
		7	Reserved	0	R	Not support
		6	Reserved	0	R	Not support
		5	Reserved	0	R	Not support
		4	Reserved	0	R	Not support
		3	Reserved	1	R	Not support
		2	M_RXBUF_OVERFLOW	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		1	M_FAULT	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
0x14	POWER_STATUS_MASK	0	M_ALARM_VBUS_VOLTAGE_L	1	R	Not support
		7	Reserved	0	R	Not support
		6	M_TCPC_INITIAL	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		5	M_SRC_NonDefault	1	R	Not support
		4	M_SRC_VBUS	1	R	Not support
		3	M_VBUS_PRESENT_DETC	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		2	M_VBUS_PRESENT	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		1	M_VCONN_PRESENT	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
0x15	FAULT_STATUS_MASK	0	M_SINK_VBUS	1	R	Not support
		7	M_VCON_OV	0	RW	0b: Interrupt masked 1b: Interrupt unmasked
		6	M_FORCE_OFF_VBUS	1	RW	0b: Interrupt masked 1b: Interrupt unmasked This field has no meaning for HUSB311
		5	M_AUTO_DISC_FAIL	1	RW	0b: Interrupt masked

Add	Register Name	Bit	Filed	Default	Type	Description
						1b: Interrupt unmasked This field has no meaning for HUSB311
		4	M_FORCE_DISCONNECT_FAIL	1	RW	0b: Interrupt masked 1b: Interrupt unmasked This field has no meaning for HUSB311
		3	M_VBUS_OC	1	RW	0b: Interrupt masked 1b: Interrupt unmasked This field has no meaning for HUSB311
		2	M_VBUS_OV	1	RW	0b: Interrupt masked 1b: Interrupt unmasked This field has no meaning for HUSB311
		1	M_VCON_OC	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
		0	M_I2C_ERROR	1	RW	0b: Interrupt masked 1b: Interrupt unmasked
0x18	CONFIG_STANDARDD_OUTPUT	7	H_IMPEDENCE	0	R	Not support
		6	DBG_ACC_CONNECT_O	0	R	Not support
		5	AUDIO_ACC_CONNECT	0	R	Not support
		4	ACTIVE_CABLE_CONNECT	0	R	Not support
		3:2	MUX_CTRL	0	R	Not support
		1	CONNECT_PRESENT	0	R	Not support
		0	CONNECT_ORIENT	0	R	Not support
0x19	TCPC_CONTROL	7	Reserved	0	R	
		6	EN_LK4CNCT_ALERT	0	RW	0b: Disable ALERT.CcStatus assertion when CC_STATUS.Looking4Connection changes 1b: Enable ALERT.CcStatus assertion when CC_STATUS.Looking4Connection changes
		5:4	Reserved	0	R	
		3:2	I2C_CHECK_STRENGTH	0	R	Not support
		1	BIST_TEST_MODE	0	RW	0: Normal Operation. Incoming messages enabled by RECEIVE_DETECT passed to TCPM via Alert 1: BIST Test Mode. Incoming messages enabled by RECEIVE_DETECT result in GoodCRC response but may not be passed to the TCPM via Alert. HUSB311 may temporarily store incoming messages in the Rx Buffer, but this may or may not result in a Receive SOP* Message Status or a Rx Buffer Overflow alert
		0	PLUG_ORIENT	0	RW	0b: When VCONN is enabled (0x1C[0]=1), apply it to the CC2 pin. Monitor the CC1 pin for BMC communications 1b: When VCONN is enabled (0x1C[0]=1), apply it to the CC1 pin. Monitor the CC2 pin for BMC communications
0x1A	ROLE_CONTROL	7	Reserved	0	R	

Add	Register Name	Bit	Filed	Default	Type	Description
		6	DRP	0	RW	0b: No DRP. Bits B3..0 determine Rp/Rd settings 1b: DRP
		5:4	RP_VALUE	0	RW	00b: Rp default 01b: Rp 1.5 A 10b: Rp 3.0 A 11b: Reserved
		3:2	CC2	10	RW	00b : Reserved 01b: Rp (Use Rp definition in B5..4) 10b : Rd 11b: Open (Disconnect or don't care)
		1:0	CC1	10	RW	00b : Reserved 01b: Rp (Use Rp definition in B5..4) 10b: Rd 11b: Open (Disconnect or don't care)
0x1B	FAULT_CONTROL	7	DIS_VCON_OV	0	RW	0b: VCONN OV Fault detection circuit enabled when EN_VCONN=1 (Reg0x1C[0]=1) 1b: VCONN OV Fault detection circuit disabled
		6:5	Reserved	0	R	Not support
		4	DIS_FORCE_OFF_VBUS	0	R	Not support
		3	DIS_VBUS_DISC_FAULT_TIMER	0	R	Not support
		2	DIS_VBUS_OC	0	R	Not support
		1	DIS_VBUS_OV	0	R	Not support
		0	DIS_VCON_OC	0	RW	0b: Fault detection circuit enabled when EN_VCONN=1 (Reg0x1C[0]=1) 1b: Fault detection circuit disabled
0x1C	POWER_CONTROL	7	Reserved	0	R	
		6	VBUS_VOL_MONITOR	0	R	Not support
		5	DIS_VOL_ALARM	0	R	Not support
		4	AUTO_DISC_DISCNCT	0	R	Not support
		3	BLEED_DISC	0	R	Not support
		2	FORCE_DISC	0	R	Not support
		1	VCONN_POWER_SPT	0	RW	0b: HUSB311 delivers at least 1W on VCONN. 1b: HUSB311 delivers at least the power indicated in <code>DEVICE_CAPABILITIES.VCONN_POWER</code>
		0	EN_VCONN	0	RW	This bit control the path from VCONN pin to the repopulated CC pin (unattached CC). 0b: Disable VCONN Path(default) 1b: Enable VCONN Source to unattached CC
0x1D	CC_STATUS	7:6	Reserved	0	R	
		5	Look4Connection	0	R	0b: the HUSB311 is NOT actively looking for a connection. A transition from 1 to 0 indicates a potential connection has been found

Add	Register Name	Bit	Filed	Default	Type	Description
						1b: the HUSB311 is looking for a connection (toggling as a DRP or looking for a connection as Sink/Source only condition)
		4	Connect_RESULT	1	R	0b: the HUSB311 is currently presenting Rp 1b: the HUSB311 is currently presenting Rd
		3:2	CC2_STATUS	0	R	<p>If (ROLE_CONTROL.CC2 = Rp) or (Connect_RESULT = 0)</p> <p>00b: SRC.Open (Open, Rp)</p> <p>01b: SRC.Ra (below maximum vRa)</p> <p>10b: SRC.Rd (within the vRd range)</p> <p>11b: reserved</p> <p>If (ROLE_CONTROL.CC2 = Rd) or (Connect_RESULT = 1)</p> <p>00b: SNK.Open (Below maximum vRa)</p> <p>01b: SNK.Default (Above minimum vRd-Connect)</p> <p>10b: SNK.Power1.5 (Above minimum vRd-Connect) Detects Rp 1.5 A</p> <p>11b: SNK.Power3.0 (Above minimum vRd-Connect) Detects Rp 3.0 A</p> <p>If ROLE_CONTROL.CC2 = 00b, this field is set to 00b</p> <p>If ROLE_CONTROL.CC2 = Open, this field is set to 00b and this change doesn't cause an Alert.CCStatus</p> <p>This field always returns 00b if (CC_STATUS[5] = 1), that means the CCStatus is not updated to these bits or (POWER_CONTROL.EN_VCONN = 1 and TCPC_CONTROL.PLUG_ORIENT = 0). Otherwise, the returned value depends upon ROLE_CONTROL.CC2</p>
		1:0	CC1_STATUS	0	R	<p>If (ROLE_CONTROL.CC1 = Rp) or (Connect_RESULT = 0)</p> <p>00b: SRC.Open (Open, Rp)</p> <p>01b: SRC.Ra (below maximum vRa)</p> <p>10b: SRC.Rd (within the vRd range)</p> <p>11b: reserved</p> <p>If (ROLE_CONTROL.CC1 = Rd) or Connect_RESULT= 1)</p> <p>00b: SNK.Open (Below maximum vRa)</p> <p>01b: SNK.Default (Above minimum vRd-Connect)</p> <p>10b: SNK.Power1.5 (Above minimum vRd-Connect) Detects Rp-1.5 A</p> <p>11b: SNK.Power3.0 (Above minimum vRd-Connect) Detects Rp-3.0 A</p> <p>If ROLE_CONTROL.CC1 = 00b, this field is set to 00b</p> <p>If ROLE_CONTROL.CC1 = Open, this field is set to 00b and this change doesn't cause an Alert.CCStatus</p> <p>This field always returns 00b if (CC_STATUS[5] = 1), that means the CCStatus is not updated to these bits or (POWER_CONTROL.EN_VCONN = 1 and TCPC_CONTROL.PLUG_ORIENT =</p>

Add	Register Name	Bit	Filed	Default	Type	Description
						1). Otherwise, the returned value depends upon ROLE_CONTROL_CC1
0x1E	POWER_STATUS	7	DBG_ACC_CONNECT	0	R	Not support
		6	TCPC_INITIAL	0	R	0b: The HUSB311 has completed initialization and all registers are valid 1b: The HUSB311 is still performing internal initialization and the only registers that are guaranteed to return the correct values are 00h..0Fh
		5	SRC_NonDefault	0	R	Not support
		4	SRC_VBUS	0	R	Not support
		3	VBUS_PRESENT_DETCT	1	R	This bit reflects the status of 0x90[1] 0b: VBUS Present Detection Disabled (Reg0x90[1]=0b) 1b: VBUS Present Detection Enabled (Reg0x90[1]=1b)
		2	VBUS_PRESENT	0	R	This bit reflects the status of VBUS. It is an edge-triggered comparator. Only a valid rising or falling edge of VBUS can change this bit. The VBUS Detection is enabled by 0x90[1]. 0b: VBUS Disconnected (VBUS<VBUS_PRIS) 1b: VBUS Connected (VBUS>VBUS_PRIS)
		1	VCONN_PRESENT	0	R	0b: VCONN is not present (VCONN<VCN_PRIS) 1b: This bit is asserted when VCONN present CC1 or CC2 (VCONN>VCN_PRIS) When POWER_CONTROL[0]=0b, this bit is set as 0
		0	SINK_VBUS	0	R	Not support
0x1F	FAULT_STATUS	7	VCON_OV	0	RW	0b: Not in an over-voltage protection state 1b: Over-voltage fault latched.
		6	FORCE_OFF_VBUS	0	R	Not support
		5	AUTO_DISC_FAIL	0	R	Not support
		4	FORCE_DISC_FAIL	0	R	Not support
		3	VBUS_OC	0	R	Not support
		2	VBUS_OV	0	R	Not support
		1	VCON_OC	0	RW	This bit is set if the current exceeds the VCON_OC. 0b: No Fault detected 1b: Over-current VCONN fault latched
		0	I ² C_ERROR	0	RW	0b: No Error 1b: I ² C error has occurred
0x20		7:0	Reserved	0	R	Not support
0x21		7:0	Reserved	0	R	Not support
0x22		7:0	Reserved	0	R	Not support
0x23	COMMAND	7:0		0x00	W	Default Value after POR
			Look4Connection	0x99	W	Start DRP Toggling if ROLE_CONTROL_DRP=1b. If ROLE_CONTROL_CC1/CC2= 01b start with

Add	Register Name	Bit	Filed	Default	Type	Description
						Rp, if ROLE_CONTROL.CC1/CC2=10b start with Rd
			RxOneMore	0xAA	W	Configure the HUSB311 to automatically clear the RECEIVE_DETECT register after sending the next GoodCRC
			ResetTransmitBuffer	0xDD	W	The HUSB311 resets the pointer of the Tx_BUFFER register to offset 1 and the contents of Tx_BUFFER becomes invalid when this COMMAND is issued by the TCPM
			ResetReceiverBuffer	0xEE	W	After receiving this COMMAND, HUSB311 resets the pointer of RECEIVE_BUFFER to 1 (0x32). This COMMAND doesn't clear the RX_BUFFER
0x24	DEVICE_CAPABILITIES_1L	7:5	ROLES_SUPPORT	110	R	000b: Type-C Port Manager can configure the Port as Source only or Sink only (not DRP) 001b: Source only 010b: Sink only 011b: Sink with accessory support (optional) 100b: DRP only 101b: Adapter or Cable (Ra) only 110b: Source, Sink, DRP, Adapter/Cable all supported 111b: Not valid
		4	ALL_SOP_SUPPORT	1	R	1b: All SOP* messages are supported
		3	SOURCE_VCONN	1	R	0b: HUSB311 is not capable of switching VCONN 1b: HUSB311 is capable of switching VCONN
		2	CPB_SINK_VBUS	0	R	Not Supported
		1	SOURCE_HV_VBUS	0	R	Not Supported
		0	SOURCE_VBUS	0	R	Not Supported
0x25	DEVICE_CAPABILITIES_1H	7	Reserved	0	R	Not Supported
		6	CPB_VBUS_OC	0	R	Not Supported
		5	CPB_VBUS_OV	0	R	Not Supported
		4	CPB_BLEED_DISC	0	R	Not Supported
		3	CPB_FORCE_DISC	0	R	Not Supported
		2	VBUS_MEASURE_ALARM	0	R	Not Supported
		1:0	SOURCE_RP_SUPPORT	10	R	00b: Rp default only 01b: Rp 1.5 A and default 10b: Rp 3.0 A, 1.5 A, and default 11b: Reserved Rp values which may be configured by the TCPM via the ROLE_CONTROL register
0x26	DEVICE_CAPABILITIES_2L	7	SINK_DISCONNECT_DET	0	R	0b: VBUS_SINK_DISCONNECT_THRESHOLD not implemented (default: Use POWER_STATUS.VBUS_PRESENT=0b to indicate a Sink disconnect)

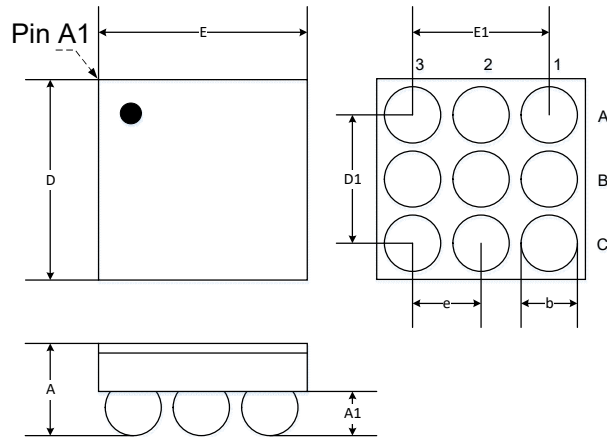
Add	Register Name	Bit	Filed	Default	Type	Description
		6	STOP_DISC_THD	0	R	0b: VBUS_STOP_DISCHARGE_THRESHOLD not implemented (default)
		5:4	VBUS_VOL_ALARM_LSB	11	R	11: reserved
		3:1	VCONN_POWER	010	R	000b: 1.0 W 001b: 1.5 W 010b: 2.0 W 011b: 3 W 100b: 4 W 101b: 5 W 110b: 6 W 111b: External
		0	VCONN_OCF	1	R	0b: HUSB311 is not capable of detecting a VCONN over-current fault 1b: HUSB311 is capable of detecting a VCONN over-current fault
0x27	DEVICE_CAPABILITIES_2H	7:0	Reserved	0	R	Not support
0x28	STANDARD_INPUT_CAPABILITIES	7:3	Reserved	0	R	Not support
		2	VBUS_EXT_OVERFLOW	0	R	Not support
		1	VBUS_EXT_OVERFLOW	0	R	Not support
		0	FORCE_OFF_VBUS_IN	0	R	Not support
0x29	STANDARD_OUTPUT_CAPABILITIES	7	Reserved	0	R	Not support
		6	CPB_DBG_ACC_IND	0	R	Not support
		5	CPB_VBUS_PRESENT_MNT	0	R	Not support
		4	CPB_AUDIO_ADT_ACC_IND	0	R	Not support
		3	CPB_ACTIVE_CABLE_IND	0	R	Not support
		2	CPB_MUX_CFG_CTRL	0	R	Not support
		1	CPB_CONNECT_PRESENT	0	R	Not support
		0	CPB_CONNECT_ORIENT	0	R	Not support
0x2E	MESSAGE_HEADER_INFO	7:5	Reserved	0	R	Not support
		4	CABLE_PLUG	0	RW	0b: Message originated from Source, Sink, or DRP 1b: Message originated from a Cable Plug
		3	DATA_ROLE	0	RW	0b: UFP 1b: DFP
		2:1	USBPD_SPECREV	01	RW	00b: Revision 1.0 01b: Revision 2.0 10b: Revision 3.0 11b: Reserved

Add	Register Name	Bit	Filed	Default	Type	Description
		0	POWER_ROLE	0	RW	0b: Sink 1b: Source
0x2F	RECEIVE_DETECT	7	Reserved	0	R	Not support
		6	EN_CABLE_RST	0	RW	0b : HUSB311 does not detect Cable Reset signaling (default) 1b : HUSB311 detects Cable Reset signaling
		5	EN_HARD_RST	0	RW	0b : HUSB311 does not detect Hard Reset signaling (default) 1b : HUSB311 detects Hard Reset signaling
		4	EN_SOP2DB	0	RW	0b : HUSB311 does not detect SOP_DBG' message (default) 1b : HUSB311 detects SOP_DBG' message
		3	EN_SOP1DB	0	RW	0b : HUSB311 does not detect SOP_DBG' message (default) 1b : HUSB311 detects SOP_DBG' message
		2	EN_SOP2	0	RW	0b : HUSB311 does not detect SOP'' message (default) 1b : HUSB311 detects SOP'' message
		1	EN_SOP1	0	RW	0b : HUSB311 does not detect SOP' message (default) 1b : HUSB311 detects SOP' message
		0	EN_SOP	0	RW	0b : HUSB311 does not detect SOP message (default) 1b : HUSB311 detects SOP message
0x30	RX_BYTE_COUNT	7:0	RX_BYTE_COUNT	0	R	This register indicates the number of bytes in the RX_BUF_BYTEx registers plus one which means the register counts from Reg0x31 to the register stored the last data byte. It is cleared as 0 when Alert.RX_SOP_MSG_STATUS is cleared. The value in this register should be less than or equal to 31. When a CableReset is received, this register value is 0x01
0x31	RX_BUF_FRAME_TYPE	7:3	Reserved	0	R	
		2:0	RX_FRAME_TYPE	0	R	Type of received frame 000b : Received SOP 001b : Received SOP' 010b : Received SOP'' 011b : Received SOP_DBG' 100b : Received SOP_DBG'' 110b : Received Cable Reset 111b: Reserved
0x32	RX_BUF_BYTE0	7:0	RX_HEAD_0	0	R	Byte 0 (bits 7..0) of message header
0x33	RX_BUF_BYTE1	7:0	RX_HEAD_1	0	R	Byte 1 (bits 15..8) of message header
0x34	RX_BUF_BYTE2	7:0	RX_OBJ1_0	0	R	Byte 0 (bits 7..0) of 1st data object
0x35	RX_BUF_BYTE3	7:0	RX_OBJ1_1	0	R	Byte 1 (bits 15..8) of 1st data object
0x36	RX_BUF_BYTE4	7:0	RX_OBJ1_2	0	R	Byte 2 (bits 23..16) of 1st data object
0x37	RX_BUF_BYTE5	7:0	RX_OBJ1_3	0	R	Byte 3 (bits 31..24) of 1st data object
0x38	RX_BUF_BYTE6	7:0	RX_OBJ2_0	0	R	Byte 0 (bits 7..0) of 2nd data object

Add	Register Name	Bit	Filed	Default	Type	Description
0x39	RX_BUF_BYTE7	7:0	RX_OBJ2_1	0	R	Byte 1 (bits 15..8) of 2nd data object
0x3A	RX_BUF_BYTE8	7:0	RX_OBJ2_2	0	R	Byte 2 (bits 23..16) of 2nd data object
0x3B	RX_BUF_BYTE9	7:0	RX_OBJ2_3	0	R	Byte 3 (bits 31..24) of 2nd data object
0x3C	RX_BUF_BYTE10	7:0	RX_OBJ3_0	0	R	Byte 0 (bits 7..0) of 3rd data object
0x3D	RX_BUF_BYTE11	7:0	RX_OBJ3_1	0	R	Byte 1 (bits 15..8) of 3rd data object
0x3E	RX_BUF_BYTE12	7:0	RX_OBJ3_2	0	R	Byte 2 (bits 23..16) of 3rd data object
0x3F	RX_BUF_BYTE13	7:0	RX_OBJ3_3	0	R	Byte 3 (bits 31..24) of 3rd data object
0x40	RX_BUF_BYTE14	7:0	RX_OBJ4_0	0	R	Byte 0 (bits 7..0) of 4th data object
0x41	RX_BUF_BYTE15	7:0	RX_OBJ4_1	0	R	Byte 1 (bits 15..8) of 4th data object
0x42	RX_BUF_BYTE16	7:0	RX_OBJ4_2	0	R	Byte 2 (bits 23..16) of 4th data object
0x43	RX_BUF_BYTE17	7:0	RX_OBJ4_3	0	R	Byte 3 (bits 31..24) of 4th data object
0x44	RX_BUF_BYTE18	7:0	RX_OBJ5_0	0	R	Byte 0 (bits 7..0) of 5th data object
0x45	RX_BUF_BYTE19	7:0	RX_OBJ5_1	0	R	Byte 1 (bits 15..8) of 5th data object
0x46	RX_BUF_BYTE20	7:0	RX_OBJ5_2	0	R	Byte 2 (bits 23..16) of 5th data object
0x47	RX_BUF_BYTE21	7:0	RX_OBJ5_3	0	R	Byte 3 (bits 31..24) of 5th data object
0x48	RX_BUF_BYTE22	7:0	RX_OBJ6_0	0	R	Byte 0 (bits 7..0) of 6th data object
0x49	RX_BUF_BYTE23	7:0	RX_OBJ6_1	0	R	Byte 1 (bits 15..8) of 6th data object
0x4A	RX_BUF_BYTE24	7:0	RX_OBJ6_2	0	R	Byte 2 (bits 23..16) of 6th data object
0x4B	RX_BUF_BYTE25	7:0	RX_OBJ6_3	0	R	Byte 3 (bits 31..24) of 6th data object
0x4C	RX_BUF_BYTE26	7:0	RX_OBJ7_0	0	R	Byte 0 (bits 7..0) of 7th data object
0x4D	RX_BUF_BYTE27	7:0	RX_OBJ7_1	0	R	Byte 1 (bits 15..8) of 7th data object
0x4E	RX_BUF_BYTE28	7:0	RX_OBJ7_2	0	R	Byte 2 (bits 23..16) of 7th data object
0x4F	RX_BUF_BYTE29	7:0	RX_OBJ7_3	0	R	Byte 3 (bits 31..24) of 7th data object
0x50	TX_BUF_FRAME_TYPE	7:6	Reserved	0	R	Not support
		5:4	TX_RETRY_CNT	0	RW	00b: No message retry is required 01b: Automatically retry message transmission once 10b: Automatically retry message transmission twice 11b: Automatically retry message transmission three times
		3	Reserved	0	R	Not support
		2:0	TX_FRAME_TYPE	0	RW	000b: Transmit SOP 001b: Transmit SOP' 010b: Transmit SOP'' 011b: Transmit SOP_DBG' 100b: Transmit SOP_DBG'' 101b: Transmit Hard Reset 110b: Transmit Cable Reset 111b: Transmit BIST Carrier Mode 2 (HUSB311 shall exit the BIST mode no later than tBISTContMode max).
0x51	TX_BYTE_COUNT	7:0	TX_BYTE_COUNT	0	RW	The number of bytes the TCPM will write
0x52	TX_BUF_BYTE0	7:0	TX_HEAD_0	0	RW	Byte 0 (bits 7..0) of message header
0x53	TX_BUF_BYTE1	7:0	TX_HEAD_1	0	RW	Byte 1 (bits 15..8) of message header
0x54	TX_BUF_BYTE2	7:0	TX_OBJ1_0	0	RW	Byte 0 (bits 7..0) of 1 st data object
0x55	TX_BUF_BYTE3	7:0	TX_OBJ1_1	0	RW	Byte 1 (bits 15..8) of 1 st data object
0x56	TX_BUF_BYTE4	7:0	TX_OBJ1_2	0	RW	Byte 2 (bits 23..16) of 1 st data object
0x57	TX_BUF_BYTE5	7:0	TX_OBJ1_3	0	RW	Byte 3 (bits 31..24) of 1 st data object

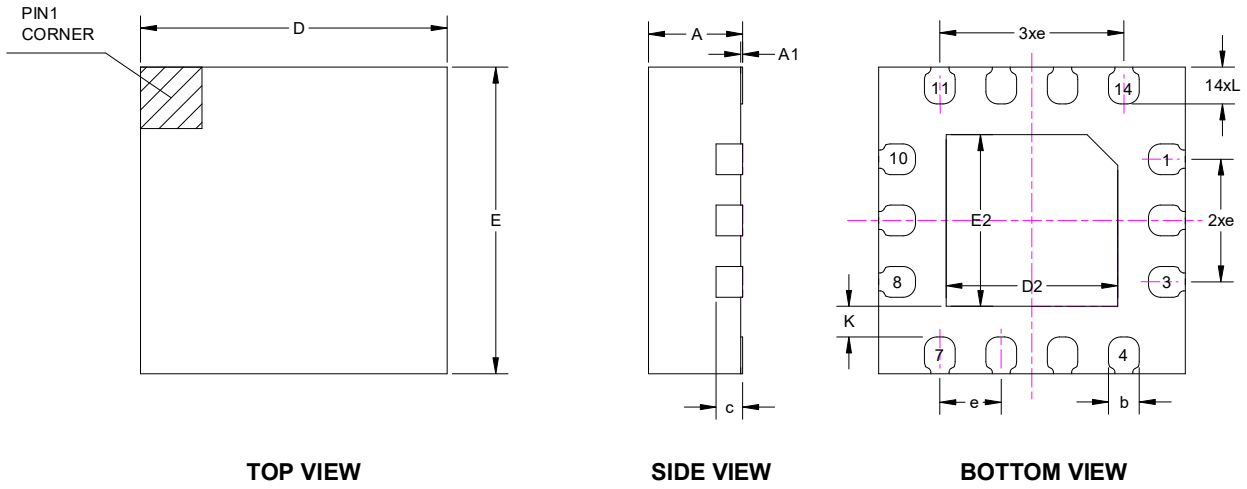
Add	Register Name	Bit	Filed	Default	Type	Description
0x58	TX_BUF_BYTE6	7:0	TX_OBJ2_0	0	RW	Byte 0 (bits 7..0) of 2 nd data object
0x59	TX_BUF_BYTE7	7:0	TX_OBJ2_1	0	RW	Byte 1 (bits 15..8) of 2 nd data object
0x5A	TX_BUF_BYTE8	7:0	TX_OBJ2_2	0	RW	Byte 2 (bits 23..16) of 2 nd data object
0x5B	TX_BUF_BYTE9	7:0	TX_OBJ2_3	0	RW	Byte 3 (bits 31..24) of 2 nd data object
0x5C	TX_BUF_BYTE10	7:0	TX_OBJ3_0	0	RW	Byte 0 (bits 7..0) of 3 rd data object
0x5D	TX_BUF_BYTE11	7:0	TX_OBJ3_1	0	RW	Byte 1 (bits 15..8) of 3 rd data object
0x5E	TX_BUF_BYTE12	7:0	TX_OBJ3_2	0	RW	Byte 2 (bits 23..16) of 3 rd data object
0x5F	TX_BUF_BYTE13	7:0	TX_OBJ3_3	0	RW	Byte 3 (bits 31..24) of 3 rd data object
0x60	TX_BUF_BYTE14	7:0	TX_OBJ4_0	0	RW	Byte 0 (bits 7..0) of 4 th data object
0x61	TX_BUF_BYTE15	7:0	TX_OBJ4_1	0	RW	Byte 1 (bits 15..8) of 4 th data object
0x62	TX_BUF_BYTE16	7:0	TX_OBJ4_2	0	RW	Byte 2 (bits 23..16) of 4 th data object
0x63	TX_BUF_BYTE17	7:0	TX_OBJ4_3	0	RW	Byte 3 (bits 31..24) of 4 th data object
0x64	TX_BUF_BYTE18	7:0	TX_OBJ5_0	0	RW	Byte 0 (bits 7..0) of 5 th data object
0x65	TX_BUF_BYTE19	7:0	TX_OBJ5_1	0	RW	Byte 1 (bits 15..8) of 5 th data object
0x66	TX_BUF_BYTE20	7:0	TX_OBJ5_2	0	RW	Byte 2 (bits 23..16) of 5 th data object
0x67	TX_BUF_BYTE21	7:0	TX_OBJ5_3	0	RW	Byte 3 (bits 31..24) of 5 th data object
0x68	TX_BUF_BYTE22	7:0	TX_OBJ6_0	0	RW	Byte 0 (bits 7..0) of 6 th data object
0x69	TX_BUF_BYTE23	7:0	TX_OBJ6_1	0	RW	Byte 1 (bits 15..8) of 6 th data object
0x6A	TX_BUF_BYTE24	7:0	TX_OBJ6_2	0	RW	Byte 2 (bits 23..16) of 6 th data object
0x6B	TX_BUF_BYTE25	7:0	TX_OBJ6_3	0	RW	Byte 3 (bits 31..24) of 6 th data object
0x6C	TX_BUF_BYTE26	7:0	TX_OBJ7_0	0	RW	Byte 0 (bits 7..0) of 7 th data object
0x6D	TX_BUF_BYTE27	7:0	TX_OBJ7_1	0	RW	Byte 1 (bits 15..8) of 7 th data object
0x6E	TX_BUF_BYTE28	7:0	TX_OBJ7_2	0	RW	Byte 2 (bits 23..16) of 7 th data object
0x6F	TX_BUF_BYTE29	7:0	TX_OBJ7_3	0	RW	Byte 3 (bits 31..24) of 7 th data object

PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max.
A	0.512	0.588	0.020	0.023
A1	0.178	0.218	0.007	0.009
b	0.245	0.285	0.010	0.012
D	1.330	1.380	0.052	0.054
D1	0.800		0.031	
E	1.380	1.430	0.054	0.056
E1	0.800		0.031	
e	0.400		0.016	

Figure 6. HUSB311_ACC & HUSB311_DCC Dimension



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.20	0.25	0.30
c	0.20REF		
D	2.40	2.50	2.60
D2	1.30	1.40	1.50
e	0.50BSC		
E	2.40	2.50	2.60
E2	1.30	1.40	1.50
L	0.25	0.30	0.35
K	0.25REF		

Figure 7. HUSB311_BLA& HUSB311_ELA Dimension

PACKAGE TOP MARKING

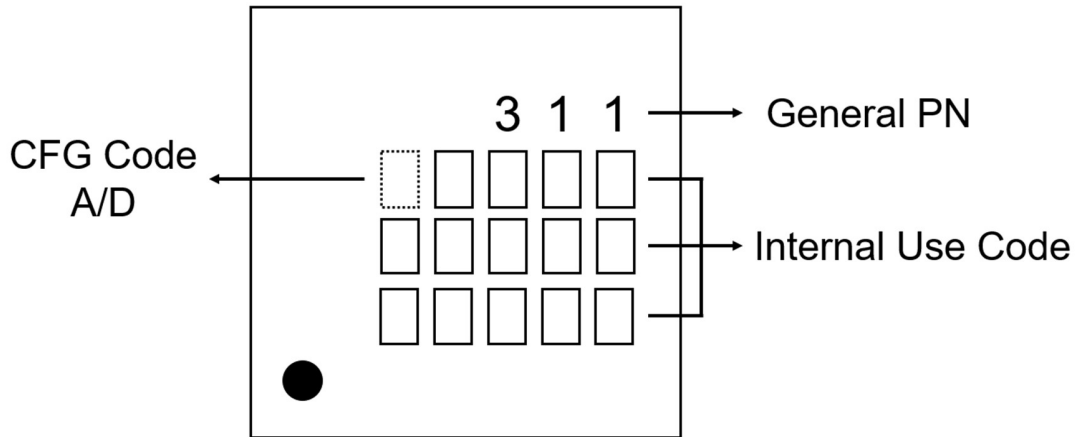


Figure 8. HUSB311_ACC & HUSB311_DCC Top Marking

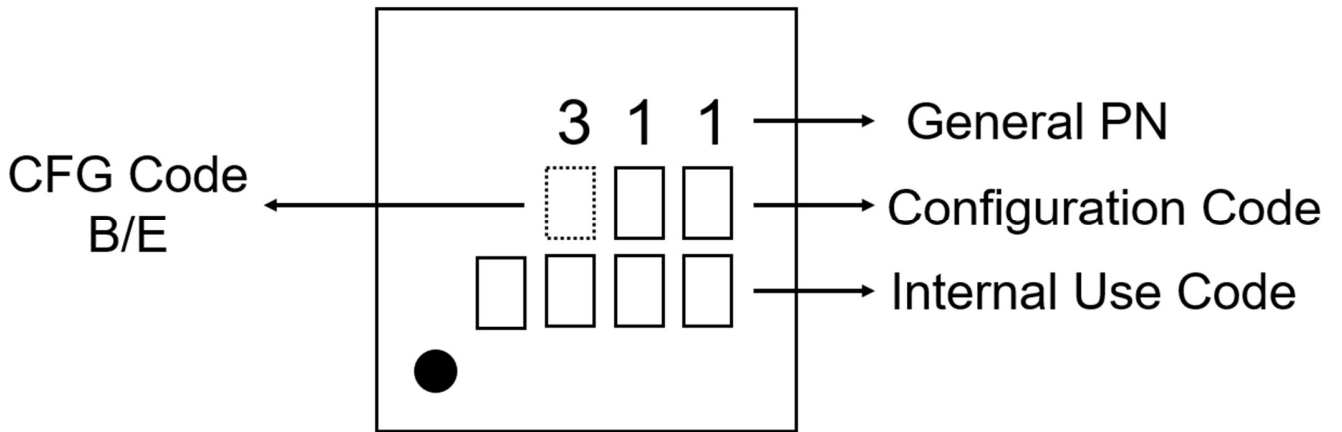
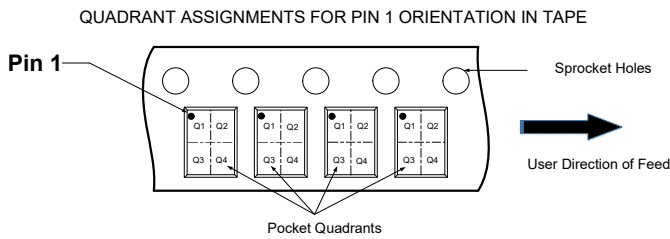
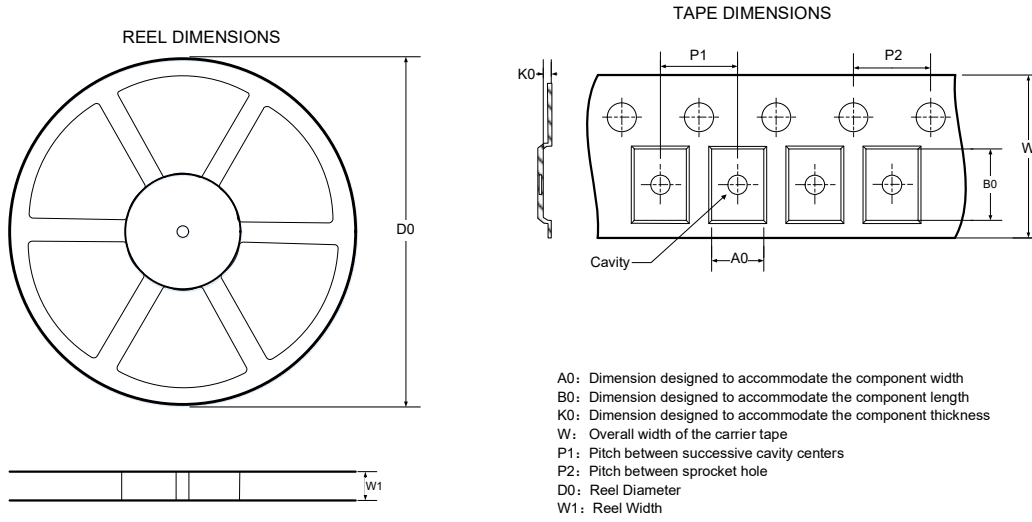


Figure 9. HUSB311_BLA & HUSB311_ELA Top Marking

ORDERING GUIDE

Model	Temperature Range	Default Role	Default I ² C Address	Package Option	Shipping Option
HUSB311_BLA	-40 °C -125 °C	SINK	0x4E	QFN-14L	Tape and Reel, 3k
HUSB311_ACC	-40 °C -125 °C	SINK	0x4E	WLCSP-9B	Tape and Reel, 3k
HUSB311_DCC	-40 °C -125 °C	SINK	0x3E	WLCSP-9B	Tape and Reel, 3k
HUSB311_ELA	-40 °C -125 °C	SINK	0x3E	QFN-14L	Tape and Reel, 3k

TAPE AND REEL INFORMATION



DIMENSIONS AND PIN1 ORIENTATION

Device	Package Type	D0 (mm)	W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant	Quantity
HUSB311_ACC HUSB311_DCC	WLCSP1.355X1.405-9B	179.00	9.00	1.52	1.52	0.78	4.00	4.00	8.00	Q1	3000
HUSB311_BLA HUSB311_ELA	QFN2.5X2.5-14L	180.00	12.80	2.75	2.75	0.85	4.00	4.00	12.00	Q1	3000

All dimensions are nominal

Figure 10. Tape and Reel Information

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